The technical areas of interest include (but not limited to):

- Theory Development on DTPI
- Information Infrastructure R&D for DTPI
- Data Analytics and Artificial Intelligence R&D for DTPI
- Applications of DTPI in Vertical Areas
  - Social Transportation
  - Power & Energy Systems
  - Autonomous Driving and Unmanned Systems
  - Oceanic Systems
  - Blockchain and Distributed Systems
  - Social System Management and Control
  - Ecology digital twins
  - Cyber-Physical Social Systems
  - Robotics
  - Manufacture Systems
- Industrial Practices of DTPI

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CALL FOR PAPERS

The digital twins (DT) and parallel intelligence recently play a central technological role in the emerging global scientific and research communities on intelligent systems. Taking place in Beijing, China, This conference series on DTPI aims to bring together academic scholars and industrial practitioners to share scientific and technological advances as well as to gain a deeper understanding of the digital twins generating real-virtual system interactions and resulting in parallel intelligence. DTPI’s particular topics also include various vertical applications of DTPI, including industrial Internet, transportation, energy, robotics, manufacturing, healthcare, etc.

DTPI 2021 will be held in Beijing China, the capital city of China and one of the world’s premier industrial, financial, and technological centers. This conference will be a distributed hybrid conference (DHC), with onsite meetings and online presentations and activities featured with a wealth of global experts and talents focusing on the R&D of digital twins and parallel intelligence.

Submissions are invited in the following categories:

- Full papers (4 pages maximum) addressing relevant DTPI topics will be peer-reviewed and, if accepted, presented at the workshop. Review, Tutorial and Vision papers are also welcome.
- Invited sessions, consisting of six full papers and/or extended abstracts, to fill a two-hour block.

The workshop program will only include papers of the highest standard as selected by the TPC, in accordance with the IEEE guidelines. All manuscripts will be accepted with the understanding that the authors will present them at the DTPI Conference. At least one author of an accepted paper will be required to register for the conference before uploading the final version. Accepted manuscript will be presented either in oral or poster format. Accepted papers will be included in the conference “preprints” and published in the online workshop proceedings. All papers and invited session proposals must be submitted through the workshop website and conform to the policy found therein.

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